

Abstract

A method of packaging electronic components includes the steps of forming a plurality of cavities (6) in a package substrate (2; 20), mounting the electronic components (8) in the cavities (6), sealing the cavities (6) with a cover substrate or a cover layer (4) and separating the components (8) packaged in this way. This permits inexpensive simultaneous production of a plurality of component packages. In one variant of the method, the components are arranged on a component carrier layer (16), the components being mounted in the cavities (6) by joining the package substrate (2; 20) and the component carrier layer (16).

Figures 1 and 2